

Bill of Materials

TI DESIGNS
TIDA-00599

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	!PCB	1		TIDA-00599	Any	Printed Circuit Board	
2	CIN, COUT	2	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1 μ F, 10 V, +/-	0402
3	GNDIN, GNDOUT	2		6092	Keystone	Standard Banana Jack, Insulated, Black	6092
4	GND_EN1-3V3, GND_EN2_IN	2		HTSW-103-07-G-S	Samtec	Header, 100mil, 3x1, Gold, TH	Header, 100mil, 3x1, TH
5	L1	1	4.7uH	EPL3010-472MLB	Coilcraft	Inductor, Shielded, Ferrite, 4.7 μ H, 0.8 A, 0.28 ohm, SMD	3.0x1.1x3.0mm
6	LBL1	1		THT-14-423-10	Brady	Thermal Transfer	PCB Label 0.650"H x 0.200"W
7	R1	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
8	SH-J1, SH-J2	2	1x2	SNT-100-BK-G	Samtec	Shunt, 100mil, Gold	Shunt
9	U1	1		LP5910-1.8YKAR	Texas Instruments	Ultra Low-Noise, 300-mA	YKA0004ACAC
10	U2	1		TPS61221DCKR	Texas Instruments	LOW INPUT VOLTAGE STEP-UP CONVERTER IN 6 PIN SC-70 PACKAGE, DCK0006A	DCK0006A
11	VIN	1		6091	Keystone	Standard Banana Jack,	6091
12	VIN LP5910	1	Double	1502-2	Keystone	Terminal, Turret, TH,	Keystone1502-2
13	VOUT 1V8, VOUT 3V3	2		108-0907-001	Emerson Network Power	BANANA JACK, 15A, Insulated, Nylon, Yellow	940x438x438mil
14	C1, C2	0	10uF	GRM188R60J106ME84	MuRata	CAP, CERM, 10 μ F, 6.3 V, +/- 20%, X5R, 0603	0603
15	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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